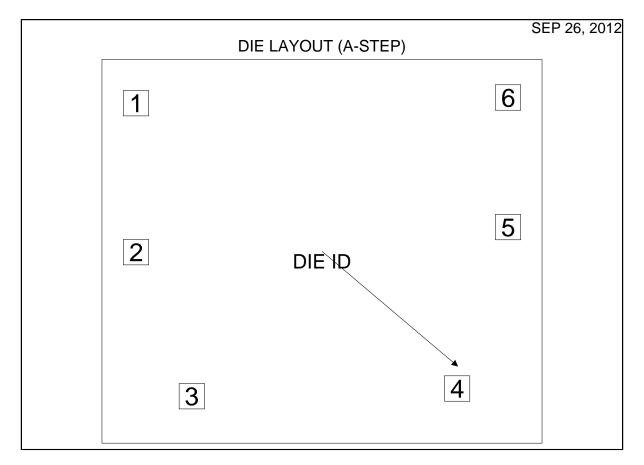


DAC121S102-MDP

12-Bit Micro Power Digital-to-Analog Converter with Rail-to-Rail



DIE/WAFER CHARACTERISTICS

| Fabrication Attributes | | General Die Information | | | | |
|---|-----------------------|-------------------------|-------------------|--|--|--|
| Physical Die | DAC121S101HR | Bond Pad Opening | 77.00µm x 77.00µm | | | |
| Identification | | Size (min) | | | | |
| Die Step | A | Bond Pad Metalization | ["AL 0.5%CU"] | | | |
| Physical Attributes | | Passivation | PECVDOX NITRIDE | | | |
| Wafer Diameter | 203mm | Back Side Metal | Bare Back | | | |
| Die Size (Drawn) | 1333.50µm x 1163.32µm | Back Side Connection | Floating or GND | | | |
| | 52.5mils x 45.8mils | | | | | |
| Thickness | 304.8µm Nominal | | | | | |
| Min Pitch | 392.85µm | | | | | |
| Note: All values are rounded to the nearest micron. | | | | | | |
| Special Assembly Requirements: | | | | | | |
| | | | | | | |
| | | | | | | |



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| (Referenced t | Die Bond Pad Coordi o die center, coordinates in | | | U. = Not U | sed | |
|---------------|---|-----------------|------|------------|-----|----|
| Signal Name | Pad Number | X/Y Coordinates | | Pad Size | | |
| | | Х | Y | Х | | Y |
| VOUT | 1 | -564 | 449 | 77 | Х | 7 |
| /SYNC | 2 | -564 | -3 | 77 | х | 77 |
| SCLK | 3 | -395 | -439 | 77 | х | 77 |
| DIN | 4 | 410 | -416 | 77 | х | 77 |
| DND | 5 | 564 | 73 | 77 | х | 77 |
| VA | 6 | 564 | 466 | 77 | х | 7 |



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| Notes | | | | | |
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